



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-02-23
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Laurent TOSI	<b>Representative Title</b>	MMS MD CHAMPION
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C64-DRMN8TP/K	PG07*24641KV	A	3068	2015-02-23
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	STD JEDEC	8	L bend	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	PGO7*24641KV					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.750	mg	supplier	die	Silicon (Si)	7440-21-3		0.719	mg	958667	8988
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	4000	38
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.003	mg	4000	38
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.002	mg	2667	25
die (s)				supplier	passivation	Indium Tin oxide ( In2O3:SnO2 )	50926-11-9		0.023	mg	30667	288
Lead-frame	Other inorganic materials	24.984	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.347	mg	974500	304339
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.586	mg	23460	7327
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.030	mg	1200	375
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.021	mg	840	262
Lead-frame Coating	Other inorganic materials	0.124	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	916800	1425
Lead-frame Coating				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	58700	91
Lead-frame Coating				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	24500	38
Die Attach	Other inorganic materials	1.027	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.925	mg	900000	11557
Die Attach				supplier	glue or soft solder	acrylate	na		0.062	mg	60000	770
Die Attach				supplier	glue or soft solder	Methacrylate	na		0.039	mg	38000	488
Die Attach				supplier	glue or soft solder	acrylate	na		0.002	mg	2000	26
Wires	Other inorganic materials	0.062	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.062	mg	1000000	776
Encapsulation	Other inorganic materials	53.051	mg	supplier	Moulding Compound	Epoxy Resin	na		3.938	mg	74233	49226
Encapsulation				supplier	Moulding Compound	Phenol Resin	na		2.625	mg	49488	32818
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		46.015	mg	867371	575184
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		0.263	mg	4949	3282
Encapsulation				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.210	mg	3959	2625
Finishing	Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	916800	14
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	1
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0